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1/3W, 0805 Low Resistance Chip Resistor (Lead / Halogen free)

1. Scope

This specification applies to 1.2mm x 2.0mm size 1/3W, fixed metal film chip resistors rectangular type for use in electronic equipment.

2. Type Designation

RL1220 ____ F (1)(2)(3) (4)Where (1) Series No. (2) Power rating F = 1/3W(3) Resistance value: For example— $R010 = 0.010 \Omega$ (4) Resistance tolerance:

- $F=\pm 1\%$ $G = \pm 2\%$ $J=\pm 5\%$
- 3. Construction and Physical Dimensions

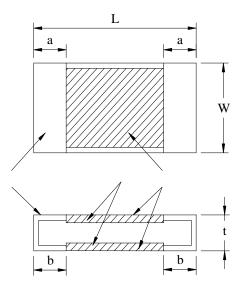


Figure 1. Structure (No mark)

Code Letter	Dimensions (mm)	
L	2.00 ± 0.20	
W	1.25 ± 0.20	
t	0.40 ± 0.20	
а	0.40 ± 0.20	
b	0.40 ± 0.20	

NOTE:

- (1) Resistive element
- (under protection film)
- (2) Electrode
- ③ Protection film
- (4) Substrate



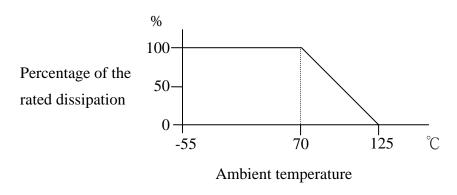
4. Ratings

4-1 Specification

Power Rating*	1/3 W	
Resistance Range	$0.010\Omega \sim 0.050\Omega$	
Resistance Tolerance	$\pm1\%$, $\pm2\%$, $\pm5\%$	
Temperature Coefficient of Resistance	0~250ppm/°C	

Note*:

Power Rating is based on continuous full load operation at rated ambient temperature of 70° C. For resistors operated at ambient temperature in excess of 70° C, the maximum load shall be derated in accordance with the following curve.





4-2 Rated Voltage

The rated voltage shall be determined by the following expression.

$$V = \sqrt{P \times R}$$
 Where V : Rated voltage (V)

R : Nominal resistance value (Ω)

P: Rated dissipation (W)

4-3 Operating and Storage Temperature Range -55 to +125 $^\circ\!\mathrm{C}$



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Characteristics		
Test Item	Condition of Test	Requirements
Short Time Overload	2.5 * Rated power for 5 seconds	$\Delta R : \pm (0.5\% + 0.0005\Omega)$
	Refer to JIS C 5201-1 4.13	Without significant damage by
		flashover (spark, arching), burn
		or breakdown etc.
Insulation Resistance	The resistor shall be cramped in the	Between Electrode and Protection
	metal block and tested , as shown below.	Film 100M Ω or over
	Test voltage : $100 \pm 15 V_{DC}$ for 1 minute	Between Electrode and Substrat
	Refer to JIS C 5201-1 4.6 Mounting	1,000M Ω or over
	condition G.	
Voltage Proof	The voltage : $100V_{AC}$ (rms.) for 1 minute	$\Delta R : \pm (0.5\% + 0.0005\Omega)$
	Refer to JIS C 5201-1 4.7	Without damage by flashover, fi
		or breakdown, as shown below.
Thermal Shock	-55 ~125℃ 5 cycles, 15 min at each	$\Delta R : \pm (1.0\% + 0.0005\Omega)$
	extreme condition	Without distinct damage in
	Refer to JIS C 5201-1 4.19	appearance
Low Temperature Storage	Kept at -55°C, 1,000 hours	$\Delta R : \pm (1.0\% + 0.0005\Omega)$
	Refer to JIS C 5201-1 4.23.4	Without distinct damage in
		appearance
High Temperature Exposure	Kept at 125°C for 1,000 hours	$\Delta R : \pm (1.0\% + 0.0005\Omega)$
	Refer to JIS C 5201-1 4.23.2	Without distinct damage in
		appearance
Solderability	Temperature of Solder : $245 \pm 5^{\circ}$ C	Uniform coating of solder cover
	Immersion Duration : 2 ± 0.5 second	minimum of 95% surface being
	Refer to JIS C 5201-1 4.17	immersed
Resistance to Soldering Heat	Dipped into solder at $270 \pm 5^{\circ}$ C	$\Delta R: \pm (0.5\% + 0.0005\Omega)$
	for 10 ± 1 seconds	Without distinct deformation in

Refer to JIS C 5201-1 4.18

appearance



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Test Item	Condition of Test	Requirements	
Load Life	Rated voltage for 1.5 hours followed by a pause 0.5 hour at $70 \pm 2^{\circ}$ C. Cycle repeated 1000 hours Refer to JIS C 5201-1 4.25	by a $\Delta R : \pm (1.0\% + 0.0005\Omega)$ Without distinct damage in appearance	
Damp Heat with Load	$60 \pm 2^{\circ}$ C with relative humidity 90% to 95%. D.C. rated voltage for 1.5 hours ON and 30 minutes OFF. Cycle repeated 1,000 hours Refer to JIS C 5201-1 4.24	$\Delta \mathbf{R} : \pm (1.0\% + 0.0005 \Omega)$ Without distinct damage in appearance	
Mechanical Shock	100 G's for 6milliseconds. 5 pulses Refer to JIS C 5201-1 4.21	$\Delta \mathbf{R} : \pm (0.5\% + 0.0005\Omega)$ Without mechanical damage such as break	
Bending Test	Glass-Epoxy board thickness : 1.6mm Bending width : 2mm Between the fulcrums : 90mm Refer to JIS C 5201-1 4.33	$\Delta R : \pm (0.5\% + 0.0005\Omega)$ Without mechanical damage such as break	



Mounting Method

(1) Mounting method according to solder bath method

Epoxy based adhesive agent shall be applied in the middle of two lands of the test board. The specimen shall be mounted in such a way that the electrode of specimen will be evenly placed in the land area and then adhesive agent shall be cured. After applying the Resin Flux with 25 weight % Methyl Alcohol, the board shall be soldered by dipping into a molten solder bath with $260 \pm 5^{\circ}$ C for 3 to 5 seconds

(2) Mounting method according to refolw soldering method

Solder paste with approximate 200 μ m thickness shall be applied to the land of test board. The specimen shall be mounted in such way that the electrodes of specimen will be evenly placed in the land area and then shall be soldered under the circumstance that the surface temperature of the board shall be raised 240 ± 5°C (peak temperature) for 5 to 10 seconds in an upper-heater oven.

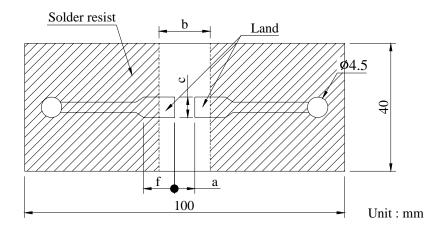
Test Board

Material : Glass Fabric Epoxy Resin (Refer to JIS C 6484)

Board thickness : 1.6mm

Copper foil thickness : 0.035mm

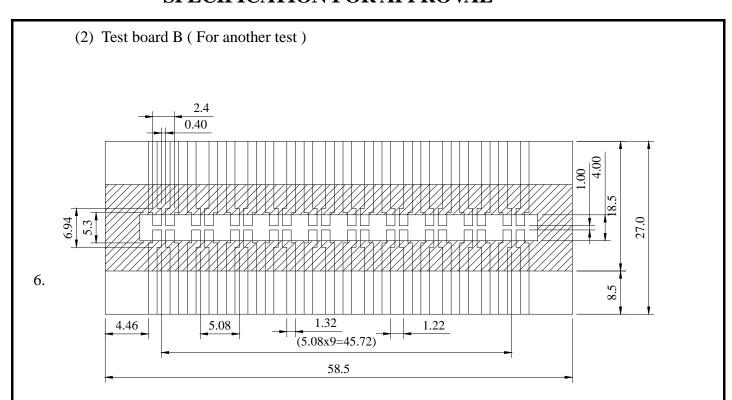
(1) Test board A (For substrate bending test)



a	b	с	f
1.2	4.0	1.65	(3.0)

SPECIFICATION FOR APPROVAL

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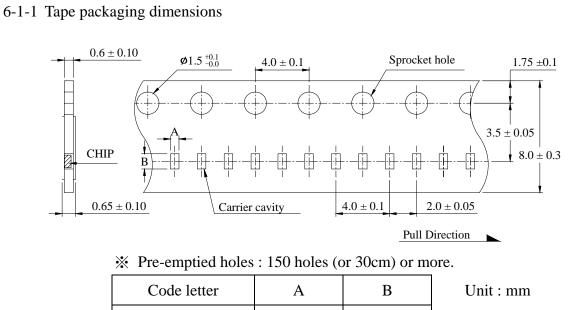


Unit : mm



6. Packaging

6-1 Dimensions

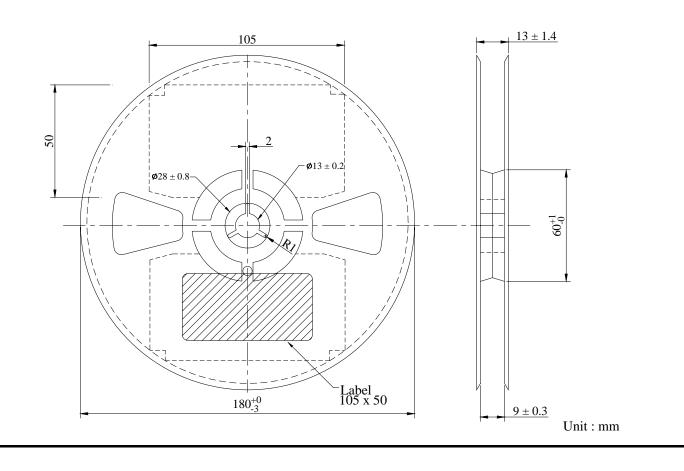


 1.45 ± 0.10

 2.25 ± 0.10

6-1-2 Reel Dimensions (Plastic reel : Correspond with EIAJ RRV08B)

Dimension



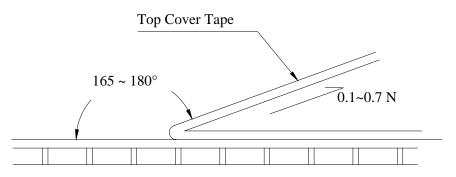


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6-2 Peel force of top cover tape

The peel speed shall be about 300 mm / min.

The peel force of top cover tape shall be between 0.1 to 0.7 N.



6-3 Numbers of taping

5,000 pieces / reel

6-4 Making

The following items shall be marked on the reel.

- (1) Type designation
- (2) Quantity
- (3) Manufacturing date code
- (4) Manufacturer's name
- (5) The country of origin